

ABSTRACT

A system may include an integrated circuit package having a package power contact and a package ground contact, and an interposer to physically receive a portion of the package and including a lip. A system may also include a first card having a card power
5 contact to interface with the package power contact and a card ground contact to interface with the package ground contact, where the first card defines an opening to receive a portion of the interposer, and the lip is to support a portion of the first card.